



# 100% Material Declaration Data Sheet for 7 Series SBG485 Package

PK630 (v1.0) December 3, 2013

**Average Weight: 1.3890 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.156648</b>	<b>11.278%</b>
	Silicon	7440-21-3	100.00	Basis	0.156648	
<b>Solder Bump</b>					<b>0.007775</b>	<b>0.560%</b>
	Tin	7440-31-5	63.00	Basis	0.004898	
	Lead	7439-92-1	37.00	Basis	0.002877	
<b>Underfill</b>					<b>0.027300</b>	<b>1.965%</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.005460	
	Phenolic Resin	Trade Secret	15.00	Basis	0.004095	
	Bisphenol A type liquid epoxy resin	25068-39-6	5.00	Basis	0.001365	
	Amine type accelerator	Trade Secret	5.00	Basis	0.001365	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.014060	
	Carbon Black	1333-86-4	1.00	Color Agent	0.000273	
	Additives	Trade Secret	2.50	Additives	0.000683	
<b>Solder Paste</b>					<b>0.002800</b>	<b>0.202%</b>
	Tin	7440-31-5	96.50	Metal	0.002702	
	Silver	7440-22-4	3.00	Metal	0.000084	
	Copper	7440-50-8	0.50	Metal	0.000014	
<b>Capacitor 1</b>					<b>0.014400</b>	<b>1.037%</b>
	BaTiO3	12047-27-7	70.60	Ceramic	0.010166	
	Nickel	7440-02-0	6.70	Inner Electrode	0.000965	
	Copper	7440-50-8	20.10	Outer Electrode	0.002894	
	Nickel	7440-02-0	0.80	Plating 1	0.000115	
	Tin	7440-31-5	1.80	Plating 2	0.000259	
<b>Capacitor 2</b>					<b>0.000600</b>	<b>0.043%</b>
	BaTiO3	12047-27-7	66.00	Ceramic	0.000396	
	Nickel	7440-02-0	2.67	Inner Electrode	0.000016	
	Copper	7440-50-8	23.33	Outer Electrode	0.000140	
	Nickel	7440-02-0	2.33	Plating 1	0.000014	
	Tin	7440-31-5	5.67	Plating 2	0.000034	

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<b>Capacitor 3</b>					<b>0.003720</b>	<b>0.268%</b>
	BaTiO3	12047-27-7	51.10	Ceramic	0.001901	
	Nickel	7440-02-0	27.00	Inner Electrode	0.001004	
	Copper	7440-5-8	16.00	Outer Electrode	0.000595	
	Glass	65997-17-3	0.90		0.000033	
	Nickel	7440-02-0	2.00	Plating 1	0.000074	
	Tin	7440-31-5	3.00	Plating 2	0.000112	
<b>Solder Ball</b>					<b>0.233980</b>	<b>16.845%</b>
	Tin	7440-31-5	96.50	Basis	0.225791	
	Silver	7440-22-4	3.00	Basis	0.007019	
	Copper	7440-50-8	0.50	Basis	0.001170	
<b>Substrate</b>					<b>0.941799</b>	<b>67.803%</b>
	Copper	7440-50-8	37.384		0.352083	
	Tin	7440-31-5	1.107		0.010423	
	Lead	7439-92-1	0.284		0.002676	
	Silver	7440-22-4	0.019		0.000182	
	BT Core	Trade Secret	47.421		0.446609	
	ABF	Trade Secret	11.282		0.106251	
	Solder Mask	Trade Secret	2.503		0.023575	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
12/03/13	1.0	Initial Xilinx release.

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